











SCDS187C - FEBRUARY 2005 - REVISED AUGUST 2018

TS5A3167

# TS5A3167 0.9- $\Omega$ 1-channel 1:1 SPST Analog Switch

#### **Features**

- Isolation in Powered-Off Mode,  $V_{CC} = 0$
- Low ON-State Resistance (0.9  $\Omega$ )
- Control Inputs Are 5.5-V Tolerant
- Low Charge Injection
- Low Total Harmonic Distortion (THD)
- 1.65-V to 5.5-V Single-Supply Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 1000-V Charged-Device Model (C101)

### 2 Applications

- Cell Phones
- **PDAs**
- Portable Instrumentation
- Audio and Video Signal Routing
- Low-Voltage Data-Acquisition Systems
- **Communication Circuits**
- Modems
- Hard Drives
- **Computer Peripherals**
- Wireless Terminals and Peripherals
- Microphone Switching Notebook Docking

### Description

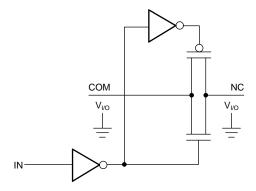
The TS5A3167 is a bidirectional, single-channel, single-pole double-throw (SPDT) analog switch that is designed to operate from 1.65 V to 5.5 V. The TS5A3167 device offers a low ON-state resistance. The device has excellent total harmonic distortion (THD) performance and consumes very low power. These features make this device suitable for portable audio applications.

### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
	SOT-23	2.90 mm x 1.60 mm
TS5A3167	SC70	2.00 mm x 1.25 mm
	DSBGA	1.50 mm x 0.90 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

#### Simple Schematic



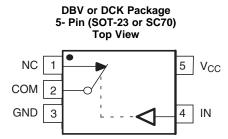


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	evision History : Page numbers for previous revisions may differ fro	om page numb	ers in the current version.	
han	ges from Revision B (March 2017) to Revision C			Page
CI	nanged the DSBGA Body Size From: 1.50 mm x 9.00	0 mm To: 1.50	mm x 0.90 mm in the Device Information table	1
	nanged the YZP package pinout view From: Top Vie			
C	anged the 12F package pillout view F10H. Top vie	W 10. Bollom	view	
han	ges from Revision A (October 2012) to Revision I	В		Page
C aı	Ided the Device Information table, Pin Configuration on ditions, Thermal Information, Detailed Description, and Implementation, Power Supply Recommendations	, Feature Desc s, Layout, Devi	ription, Device Functional Modes, Application ce and Documentation Support	
R	emoved ORDERING INFORMATION table			1
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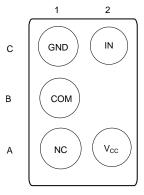
## 5 Pin Configuration and Functions



### **Pin Functions**

PIN NUMBER	NAME	DESCRIPTION
1	NC	Normally Closed
2	COM	Common
3	GND	Ground
4	IN	Digital control pin, COM connected to NC when logic low
5	V <sub>cc</sub>	Power Supply

#### YZP Package 5-Pin (DSBGA) Bottom View



### **Pin Functions**

PIN NUMBER	NAME	DESCRIPTION
A1	NC	Normally Closed
B1	COM	Common
C1	GND	Ground
A2	V <sub>CC</sub>	Power Supply
C2	IN	Digital control pin, COM connected to NC when logic low

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### 6 Specifications

## 6.1 Absolute Maximum Ratings<sup>(1)(2)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range <sup>(3)</sup>		-0.5	6.5	V
$V_{NC} \ V_{COM}$	Analog voltage range <sup>(3)(4)(5)</sup>	(4)(5)		V <sub>CC</sub> + 0.5	V
I <sub>K</sub>	Analog port diode current	$V_{NC}$ , $V_{COM} < 0$	-50		mA
I <sub>NC</sub>	On-state switch current	V V Oto V	-200	200	^
I <sub>COM</sub>	On-state peak switch current (6)	$V_{NC}$ , $V_{COM} = 0$ to $V_{CC}$	-400	400	mA
$V_{I}$	Digital input voltage range (3)(4)		-0.5	6.5	V
$I_{lK}$	Digital clamp current	V <sub>I</sub> < 0	-50		mA
Icc	Continuous current through V <sub>CC</sub>			100	mA
I <sub>GND</sub>	Continuous current through GND		-100		mA
T <sub>stg</sub>	Storage temperature range		-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.
- (3) All voltages are with respect to ground, unless otherwise specified.
- (4) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (5) This value is limited to 5.5 V maximum.
- (6) Pulse at 1-ms duration < 10% duty cycle.

### 6.2 ESD Ratings

			VALUE	UNIT
		Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	±2000	
V <sub>(ESD)</sub>	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1000	V

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	1.65	5.5	V
$V_{NC} \ V_{COM}$	Analog voltage range	0	V <sub>CC</sub>	V
$V_{I}$	Digital input voltage range	0	$V_{CC}$	V

### 6.4 Thermal Information

	THERMAL METRIC <sup>(1)</sup>	DBV (SOT-23)	DCK (SOT-23)	YZP (DSBGA)	UNIT
		5 PINS	5 PINS	5 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	230.3	268.0	146.2	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	111.9	171.8	1.4	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	69.5	64.5	39.3	°C/W
ΨЈТ	Junction-to-top characterization parameter	33.0	40.5	0.7	°C/W
ΨЈВ	Junction-to-board characterization parameter	69.0	62.9	39.8	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	n/a	n/a	n/a	°C/W

For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

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# 6.5 Electrical Characteristics for 5-V Supply<sup>(1)</sup>

 $V_{CC}$  = 4.5 V to 5.5 V,  $T_A$  = -40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDI	TIONS	$T_A$	V <sub>CC</sub>	MIN	TYP	MAX	UNIT
Analog Switch									
Peak ON resistance	r <sub>peak</sub>	0 ≤ V <sub>NC</sub> ≤ V <sub>CC</sub> ,	Switch ON,	25°C	4.5 V		0.8	1.1	Ω
	poun	$I_{COM} = -100 \text{ mA},$	See Figure 13	Full				1.2	
ON-state resistance	r <sub>on</sub>	$V_{NC} = 2.5 \text{ V},$ $I_{COM} = -100 \text{ mA},$	Switch ON, See Figure 13	25°C Full	4.5 V		0.75	0.9	Ω
ON-state resistance		$0 \le V_{NC} \le V_{CC}$ , $I_{COM} = -100 \text{ mA}$ ,	Switch ON.	25°C			0.2		
flatness	$r_{on(flat)}$	V <sub>NC</sub> = 1 V, 1.5 V, 2.5 V,	See Figure 13	25°C	4.5 V		0.15	0.25	Ω
		$I_{COM} = -100 \text{ mA},$		Full				0.25	
		V <sub>NC</sub> = 1 V,		25°C		0	4	20	
NC OFF leakage current	I <sub>NC(OFF)</sub>	$\begin{aligned} &V_{COM} = 4.5 \text{ V,} \\ &\text{or} \\ &V_{NC} = 4.5 \text{ V,} \\ &V_{COM} = 1 \text{ V,} \end{aligned}$	Switch OFF, See Figure 14	Full	5.5 V	-150		150	nA
		$V_{NC} = 0 \text{ to } 5.5 \text{ V},$		25°C	0 V	-10	0.2	10	μA
	I <sub>NC(PWROFF)</sub>	$V_{COM} = 5.5 \text{ V to } 0,$		Full	UV	-50		50	μΑ
		$V_{COM} = 1 V$		25°C		0	4	20	
COM OFF leakage current	I <sub>COM(OFF)</sub>	$\begin{split} &V_{NC}=4.5 \text{ V},\\ &\text{or}\\ &V_{COM}=4.5 \text{ V},\\ &V_{NC}=1 \text{ V}, \end{split}$	Switch OFF, See Figure 14	Full	5.5 V	-150		150	nA
		$V_{COM} = 5.5 \text{ V to } 0,$		25°C	0.17	-10	0.2	10	
	I <sub>COM(PWROFF)</sub>	$V_{NC} = 0 \text{ to } 5.5 \text{ V},$		Full	0 V	-50		50	μΑ
		V <sub>NC</sub> = 1 V,		25°C		-5	0.4	5	
NC ON leakage current	I <sub>NC(ON)</sub>	$V_{COM} = Open,$ or $V_{NC} = 4.5 \text{ V},$ $V_{COM} = Open,$	Switch ON, See Figure 15	Full	5.5 V	-50		50	nA
		$V_{COM} = 1 V$ ,		25°C		-5	0.4	5	
COM ON leakage current	I <sub>COM(ON)</sub>	$V_{NC} = \text{Open},$ or $V_{COM} = 4.5 \text{ V},$ $V_{NC} = \text{Open},$	Switch ON, See Figure 15	Full	5.5 V	-20		20	nA
Digital Control Input	s (IN)				+	1		ļ	
Input logic high	V <sub>IH</sub>			Full		2.4		5.5	V
Input logic low	V <sub>IL</sub>			Full		0		0.8	V
Input leakage		V 55V 0		25°C	5.5.1	-2	0.3	2	2
current	$I_{1H}$ , $I_{1L}$	$V_1 = 5.5 \text{ V or } 0$		Full	5.5 V	-20		20	nA

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.



# 6.6 Electrical Characteristics for 5-V Supply<sup>(1)</sup> (continued)

 $V_{CC} = 4.5 \text{ V}$  to 5.5 V,  $T_A = -40^{\circ}\text{C}$  to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CO	ONDITIONS	T <sub>A</sub>	VCC	MIN	TYP	MAX	UNIT
Dynamic	<u> </u>	-			<u> </u>				
		V - V	C = 25 pE	25°C	5 V	1	4.5	7.5	
Turn-on time	t <sub>ON</sub>	$V_{COM} = V_{CC},$ $R_L = 50 \Omega,$	C <sub>L</sub> = 35 pF, See Figure 17	Full	4.5 V to 5.5 V	1		9	ns
		V V	C 25 nF	25°C	5 V	4.5	8	11	
Turn-off time	t <sub>OFF</sub>	$V_{COM} = V_{CC},$ $R_L = 50 \Omega,$	C <sub>L</sub> = 35 pF, See Figure 17	Full	4.5 V to 5.5 V	3.5		13	ns
Charge injection	$Q_{C}$	$V_{GEN} = 0,$ $R_{GEN} = 0$ ,	C <sub>L</sub> = 1 nF, See Figure 20	25°C	5 V		6		рC
NC OFF capacitance	C <sub>NC(OFF)</sub>	$V_{NC} = V_{CC}$ or GND,	Switch OFF, See Figure 16	25°C	5 V		19		pF
COM OFF capacitance	C <sub>COM(OFF)</sub>	$V_{COM} = V_{CC}$ or GND,	Switch OFF, See Figure 16	25°C	5 V		18		pF
NC ON capacitance	C <sub>NC(ON)</sub>	$V_{NC} = V_{CC}$ or GND,	Switch ON, See Figure 16	25°C	5 V		35.5		pF
COM ON capacitance	C <sub>COM(ON)</sub>	$V_{COM} = V_{CC}$ or GND,	Switch ON, See Figure 16	25°C	5 V		35.5		pF
Digital input capacitance	Cı	$V_I = V_{CC}$ or GND,	See Figure 16	25°C	5 V		2		pF
Bandwidth	BW	$R_L = 50 \Omega$ ,	Switch ON, See Figure 18	25°C	5 V		150		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , f = 1 MHz,	Switch OFF, See Figure 19	25°C	5 V		-62		dB
Total harmonic distortion	THD	$R_L = 600 \Omega,$ $C_L = 50 pF,$	f = 20 Hz to 20 kHz, See Figure 21	25°C	5 V	C	0.005%		
Supply									
Positive supply	ı	$V_1 = V_{CC}$ or GND,	Switch ON or OFF	25°C	5.5 V		0.01	0.1	
current	I <sub>CC</sub>	VI = VCC OF GIVD,	SWILLIN ON OF OFF	Full	5.5 V			1	μΑ

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.



# 6.7 Electrical Characteristics for 3.3-V Supply<sup>(1)</sup>

 $V_{CC} = 3 \text{ V to } 3.6 \text{ V}, T_A = -40^{\circ}\text{C to } 85^{\circ}\text{C} \text{ (unless otherwise noted)}$ 

PARAMETER	SYMBOL	TEST CON	IDITIONS	$T_A$	V <sub>cc</sub>	MIN	TYP	MAX	UNIT
Analog Switch									
Peak ON resistance	r <sub>peak</sub>	$0 \le V_{NC} \le V_{CC}$ , $I_{COM} = -100 \text{ mA}$ ,	Switch ON, See Figure 13	25°C Full	3 V		1.3	1.6 1.8	Ω
							4.4	_	
ON-state resistance	r <sub>on</sub>	$V_{NC} = 2 V,$ $I_{COM} = -100 \text{ mA},$	Switch ON, See Figure 13	25°C Full	3 V		1.1	1.5	Ω
ON-state resistance		$0 \le V_{NC} \le V_{CC}$ , $I_{COM} = -100 \text{ mA}$ ,	Switch ON,	25°C			0.3		
flatness	r <sub>on(flat)</sub>	$V_{NC} = 2 \text{ V}, 0.8 \text{ V},$	See Figure 13	25°C	3 V		0.15	0.25	Ω
		$I_{COM} = -100 \text{ mA},$		Full				0.25	
		$V_{NC} = 1 V,$ $V_{COM} = 3 V,$		25°C		-5	0.5	5	
NC OFF leakage current	I <sub>NC(OFF)</sub>	or V <sub>NC</sub> = 3 V, V <sub>COM</sub> = 1 V,	Switch OFF, See Figure 14	Full	3.6 V	-50		50	nA
		$V_{NC} = 0 \text{ to } 3.6 \text{ V},$		25°C	0 V	-5	0.1	5	
	I <sub>NC(PWROFF)</sub>	$V_{COM} = 3.6 \text{ V to } 0,$		Full	0 0	-25		25	μΑ
		$V_{COM} = 1 V$ ,		25°C		-5	0.5	5	
COM OFF leakage current	I <sub>COM(OFF)</sub>	$V_{NC} = 3 \text{ V},$ or $V_{COM} = 3 \text{ V},$ $V_{NC} = 1 \text{ V},$	Switch OFF, See Figure 14	Full	3.6 V	-50		50	nA
		$V_{COM} = 3.6 \text{ V to 0},$		25°C	0.14	-5	0.1	5	
	I <sub>COM(PWROFF)</sub>	$V_{NC} = 0 \text{ to } 3.6 \text{ V},$		Full	0 V	-25		25	μA
		V <sub>NC</sub> = 1 V,		25°C		-2	0.3	2	
NC ON leakage current	I <sub>NC(ON)</sub>	$V_{COM} = Open,$ or $V_{NC} = 3 V,$ $V_{COM} = Open,$	Switch ON, See Figure 15	Full	3.6 V	-20		20	nA
		$V_{COM} = 1 V$ ,		25°C		-2	0.3	2	
COM ON leakage current	I <sub>COM(ON)</sub>	$V_{NC}$ = Open, or $V_{COM}$ = 3 V, $V_{NC}$ = Open,	Switch ON, See Figure 15	Full	3.6 V	-20		20	nA
<b>Digital Control Inputs</b>	(IN)								
Input logic high	V <sub>IH</sub>			Full		2		5.5	V
Input logic low	V <sub>IL</sub>			Full		0		8.0	V
Input lookaga aurrant	1 1	V - F F V or 0		25°C	261/	-2	0.3	2	nΛ
Input leakage current	I <sub>IH</sub> , I <sub>IL</sub>	V <sub>I</sub> = 5.5 V or 0		Full	3.6 V	-20		20	nA

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.



# 6.8 Electrical Characteristics for 3.3-V Supply<sup>(1)</sup> (continued)

 $V_{CC} = 3 \text{ V to } 3.6 \text{ V}, T_A = -40^{\circ}\text{C to } 85^{\circ}\text{C} \text{ (unless otherwise noted)}$ 

PARAMETER	SYMBOL	TEST CO	NDITIONS	T <sub>A</sub>	VCC	MIN	TYP	MAX	UNIT
Dynamic									
		V	C <sub>L</sub> = 35 pF,	25°C	3.3 V	1.5	5	9.5	
Turn-on time	t <sub>ON</sub>	$V_{COM} = V_{CC},$ $R_L = 50 \Omega,$	See Figure 17	Full	3 V to 3.6 V	1.0		10	ns
		$V_{COM} = V_{CC}$	$C_1 = 35 \text{ pF},$	25°C	3.3 V	4.5	8.5	11	
Turn-off time	t <sub>OFF</sub>	$R_L = 50 \Omega$	See Figure 17	Full	3 V to 3.6 V	3		12.5	ns
Charge injection	Q <sub>C</sub>	$V_{GEN} = 0,$ $R_{GEN} = 0,$	$C_L = 1 \text{ nF},$ See Figure 20	25°C	3.3 V		6		рС
NC OFF capacitance	C <sub>NC(OFF)</sub>	$V_{NC} = V_{CC}$ or GND,	Switch OFF, See Figure 16	25°C	3.3 V		19.5		pF
COM OFF capacitance	C <sub>COM(OFF)</sub>	$V_{COM} = V_{CC}$ or GND,	Switch OFF, See Figure 16	25°C	3.3 V		18.5		pF
NC ON capacitance	C <sub>NC(ON)</sub>	$V_{NC} = V_{CC}$ or GND,	Switch ON, See Figure 16	25°C	3.3 V		36		pF
COM ON capacitance	C <sub>COM(ON)</sub>	$V_{COM} = V_{CC}$ or GND,	Switch ON, See Figure 16	25°C	3.3 V		36		pF
Digital input capacitance	Cı	$V_I = V_{CC}$ or GND,	See Figure 16	25°C	3.3 V		2		pF
Bandwidth	BW	$R_L = 50 \Omega$ ,	Switch ON, See Figure 18	25°C	3.3 V		150		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , $f = 1 MHz$ ,	Switch OFF, See Figure 19	25°C	3.3 V		-62		dB
Total harmonic distortion	THD	$R_L = 600 \Omega,$ $C_L = 50 pF,$	f = 20 Hz to 20 kHz, See Figure 21	25°C	3.3 V		0.01%		
Supply				-					-
Positive supply		$V_{I} = V_{CC}$ or GND,	Switch ON or OFF	25°C	3.6 V		0.001	0.05	^
current	I <sub>CC</sub>	VI = VCC OI GIVD,	SWILLII ON OI OFF	Full	3.0 V			0.3	μΑ

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.



# 6.9 Electrical Characteristics for 2.5-V Supply<sup>(1)</sup>

 $V_{CC}$  = 2.3 V to 2.7 V,  $T_A$  = -40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CON	DITIONS	T <sub>A</sub>	V <sub>cc</sub>	MIN	TYP	MAX	UNIT
Analog Switch									
Peak ON resistance	r <sub>peak</sub>	$0 \le V_{NC} \le V_{CC}$	Switch ON,	25°C	2.3 V		1.8	2.4	Ω
Tour Off Tooloid 100	реак	$I_{COM} = -100 \text{ mA},$	See Figure 13	Full	2.0 1			2.6	
ON-state resistance	r <sub>on</sub>	$V_{NC} = 2 V$ ,	Switch ON,	25°C	2.3 V		1.2	2.1	Ω
	·on	$I_{COM} = -100 \text{ mA},$	See Figure 13	Full	2.0 1			2.4	
ON-state resistance		$0 \le V_{NC} \le V_{CC}$ , $I_{COM} = -100 \text{ mA}$ ,	Switch ON.	25°C			0.7		
flatness	r <sub>on(flat)</sub>	$V_{NC} = 2 \text{ V}, 0.8 \text{ V},$	See Figure 13	25°C	2.3 V		0.4	0.6	Ω
		$I_{COM} = -100 \text{ mA},$		Full				0.6	
		$V_{NC} = 1 V$		25°C		<b>-</b> 5	0.3	5	
NC OFF leakage current	I <sub>NC(OFF)</sub>	$V_{COM} = 3 \text{ V},$ or $V_{NC} = 3 \text{ V},$ $V_{COM} = 1 \text{ V},$	Switch OFF, See Figure 14	Full	2.7 V	-50		50	nA
	1	$V_{NC} = 0 \text{ to } 3.6 \text{ V},$		25°C	0.1/	-2	0.05	2	
	I <sub>NC(PWROFF)</sub>	$V_{COM} = 3.6 \text{ V to } 0,$		Full	0 V	-15		15	μΑ
		$V_{COM} = 1 V$ ,		25°C		<b>-</b> 5	0.3	5	nA
COM OFF leakage current	I <sub>COM(OFF)</sub>	$V_{NC} = 3 V$ , or $V_{COM} = 3 V$ , $V_{NC} = 1 V$ ,	Switch OFF, See Figure 14	Full	2.7 V	-50		50	
		V <sub>COM</sub> = 3.6 V to 0, V <sub>NC</sub> = 0 to 3.6 V,		25°C	0 V	-2	0.05	2	^
				Full		-15		15	μA
		V <sub>NC</sub> = 1 V,		25°C		-2	0.3	2	
NC ON leakage current	I <sub>NC(ON)</sub>	$V_{COM}$ = Open, or $V_{NC}$ = 3 V, $V_{COM}$ = Open,	Switch ON, See Figure 15	Full	2.7 V	-20		20	nA
		$V_{COM} = 1 V$ ,		25°C		-2	0.3	2	
COM ON leakage current	I <sub>COM(ON)</sub>	V <sub>NC</sub> = Open, or V <sub>COM</sub> = 3 V, V <sub>NC</sub> = Open,	Switch ON, See Figure 15	Full	2.7 V	-20		20	nA
Digital Control Inputs	(IN)	,							
Input logic high	V <sub>IH</sub>			Full		1.8		5.5	V
Input logic low	V <sub>IL</sub>			Full		0		0.6	V
Innut lookogo oursest		V		25°C	271/	-2	0.3	2	<b>~</b> ^
Input leakage current	I <sub>IH</sub> , I <sub>IL</sub>	$V_1 = 5.5 \text{ V or } 0$		Full	2.7 V	-20		20	nA

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.



# 6.10 Electrical Characteristics for 2.5-V Supply<sup>(1)</sup> (continued)

 $V_{CC} = 2.3 \text{ V}$  to 2.7 V,  $T_A = -40^{\circ}\text{C}$  to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CO	NDITIONS	$T_A$	VCC	MIN	TYP	MAX	UNIT
Dynamic									
		\/ - \/	$C_1 = 35 \text{ pF},$	25°C	2.5 V	2	6	10	
Turn-on time	t <sub>ON</sub>	$V_{COM} = V_{CC},$ $R_L = 50 \Omega,$	See Figure 17	Full	2.3 V to 2.7 V	1		12	ns
		V V	C 25 pF	25°C	2.5 V	4.5	8	10.5	
Turn-off time	t <sub>OFF</sub>	$V_{COM} = V_{CC},$ $R_L = 50 \Omega,$	C <sub>L</sub> = 35 pF, See Figure 17	Full	2.3 V to 2.7 V	3		15	ns
Charge injection	Q <sub>C</sub>	$V_{GEN} = 0,$ $R_{GEN} = 0,$	C <sub>L</sub> = 1 nF, See Figure 20	25°C	2.5 V		4		pC
NC OFF capacitance	C <sub>NC(OFF)</sub>	$V_{NC} = V_{CC}$ or GND,	Switch OFF, See Figure 16	25°C	2.5 V		19.5		pF
COM OFF capacitance	C <sub>COM(OFF)</sub>	$V_{COM} = V_{CC}$ or GND,	Switch OFF, See Figure 16	25°C	2.5 V		18.5		pF
NC ON capacitance	C <sub>NC(ON)</sub>	$V_{NC} = V_{CC}$ or GND,	Switch ON, See Figure 16	25°C	2.5 V		36.5		pF
COM ON capacitance	C <sub>COM(ON)</sub>	$V_{COM} = V_{CC}$ or GND,	Switch ON, See Figure 16	25°C	2.5 V		36.5		pF
Digital input capacitance	Cı	$V_I = V_{CC}$ or GND,	See Figure 16	25°C	2.5 V		2		pF
Bandwidth	BW	$R_L = 50 \Omega$ ,	Switch ON, See Figure 18	25°C	2.5 V		150		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , f = 1 MHz,	Switch OFF, See Figure 19	25°C	2.5 V		-62		dB
Total harmonic distortion	THD	$R_L = 600 \Omega,$ $C_L = 50 pF,$	f = 20 Hz to 20 kHz, See Figure 21	25°C	2.5 V		0.02%		
Supply									
Positive supply	I V - V or CND		Switch ON or OFF	25°C	2.7 V		0.001	0.02	μA
current	Icc	$V_I = V_{CC}$ or GND,	GWILGIT ON OF OFF	Full	Z.1 V			0.25	μΛ

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.



# 6.11 Electrical Characteristics for 1.8-V Supply<sup>(1)</sup>

 $V_{CC}$  = 1.65 V to 1.95 V,  $T_A$  = -40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CON	DITIONS	TA	V <sub>cc</sub>	MIN	TYP	MAX	UNIT
Analog Switch									
Peak ON resistance	r <sub>peak</sub>	$0 \le V_{NC} \le V_{CC},$ $I_{COM} = -100 \text{ mA},$	Switch ON, See Figure 13	25°C Full	1.65 V		4.2	25 30	Ω
ON-state resistance	r <sub>on</sub>	$V_{NC} = 2 V$ , $I_{COM} = -100 \text{ mA}$ ,	Switch ON, See Figure 13	25°C Full	1.65 V		1.6	3.9 4.0	Ω
ON-state resistance		$0 \le V_{NC} \le V_{CC}$ , $I_{COM} = -100 \text{ mA}$ ,	Switch ON.	25°C			2.8		
flatness	r <sub>on(flat)</sub>	$V_{NC} = 2 \text{ V}, 0.8 \text{ V},$ $I_{COM} = -100 \text{ mA},$	See Figure 13	25°C Full	1.65 V		4.1	22 27	Ω
		V <sub>NC</sub> = 1 V,		25°C		<b>-</b> 5		5	
NC OFF leakage current	I <sub>NC(OFF)</sub>	$V_{COM} = 3 \text{ V},$ or $V_{NC} = 3 \text{ V},$ $V_{COM} = 1 \text{ V},$	Switch OFF, See Figure 14	Full	1.95 V	-50		50	nA
		$V_{NC} = 0 \text{ to } 3.6 \text{ V},$		25°C	0 V	-2		2	
	I <sub>NC(PWROFF)</sub>	$V_{COM} = 3.6 \text{ V to } 0,$	<sub>1</sub> = 3.6 V to 0,			-10		10	μΑ
		$V_{COM} = 1 V$ ,		25°C		<b>-</b> 5		5	
COM OFF leakage current	I <sub>COM(PWROFF)</sub>	V <sub>NC</sub> = 3 V, or V <sub>COM</sub> = 3 V, V <sub>NC</sub> = 1 V, Switch OFF, See Figure 14	Full	1.95 V	-50		50	nA	
		$V_{COM} = 0 \text{ to } 3.6 \text{ V},$	<sub>OM</sub> = 0 to 3.6 V,		0.17	-2		2	
		$V_{NC} = 3.6 \text{ V to 0},$		Full	0 V	-10		10	μΑ
		V <sub>NC</sub> = 1 V,		25°C		-2		2	
NC ON leakage current	I <sub>NC(ON)</sub>	$V_{COM} = Open,$ or $V_{NC} = 3 V,$ $V_{COM} = Open,$	Switch ON, See Figure 15	Full	1.95 V	-20		20	nA
		$V_{COM} = 1 V$ ,		25°C		-2		2	
COM ON leakage current	I <sub>COM(ON)</sub>	V <sub>NC</sub> = Open, or V <sub>COM</sub> = 3 V, V <sub>NC</sub> = Open,	Switch ON, See Figure 15	Full	1.95 V	-20		20	nA
Digital Control Inputs	(IN)	•		•	•	•		•	
Input logic high	V <sub>IH</sub>			Full		1.5		5.5	V
Input logic low	V <sub>IL</sub>			Full		0		0.6	V
		V 55V 3		25°C	4.0= \(\cdot\)	-2	0.3	2	
Input leakage current	I <sub>IH</sub> , I <sub>IL</sub>	$V_1 = 5.5 \text{ V or } 0$		Full	1.95 V	-20		20	nA
		+							

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.



# 6.12 Electrical Characteristics for 1.8-V Supply<sup>(1)</sup> (continued)

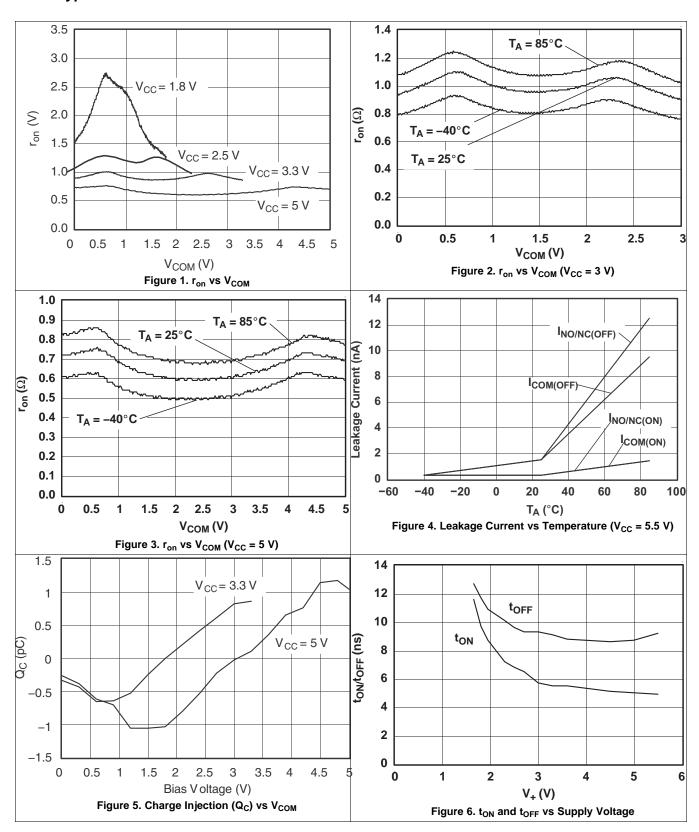
 $V_{CC}$  = 1.65 V to 1.95 V,  $T_A$  = -40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CO	NDITIONS	T <sub>A</sub>	VCC	MIN	TYP	MAX	UNIT
Dynamic									
		V - V	$C_1 = 35 pF$ ,	25°C	1.8 V	3	9	18	
Turn-on time	t <sub>ON</sub>	$V_{COM} = V_{CC},$ $R_L = 50 \Omega,$	See Figure 17	Full	1.65 V to 1.95 V	1		20	ns
		N/ N/	0 05 = 5	25°C	1.8 V	5	10	15.5	
Turn-off time	t <sub>OFF</sub>	$V_{COM} = V_{CC},$ $R_L = 50 \Omega,$	C <sub>L</sub> = 35 pF, See Figure 17	Full	1.65 V to 1.95 V	4		18.5	ns
Charge injection	Q <sub>C</sub>	$V_{GEN} = 0,$ $R_{GEN} = 0,$	C <sub>L</sub> = 1 nF, See Figure 20	25°C	1.8 V		2		рС
NC OFF capacitance	C <sub>NC(OFF)</sub>	$V_{NC} = V_{CC}$ or GND,	Switch OFF, See Figure 16	25°C	1.8 V		19.5		pF
COM OFF capacitance	C <sub>COM(OFF)</sub>	$V_{COM} = V_{CC}$ or GND,	Switch OFF, See Figure 16	25°C	1.8 V		18.5		pF
NC ON capacitance	C <sub>NC(ON)</sub>	$V_{NC} = V_{CC}$ or GND,	Switch ON, See Figure 16	25°C	1.8 V		36.5		pF
COM ON capacitance	C <sub>COM(ON)</sub>	$V_{COM} = V_{CC}$ or GND,	Switch ON, See Figure 16	25°C	1.8 V		36.5		pF
Digital input capacitance	Cı	$V_I = V_{CC}$ or GND,	See Figure 16	25°C	1.8 V		2		pF
Bandwidth	BW	$R_L = 50 \Omega$ ,	Switch ON, See Figure 18	25°C	1.8 V		150		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , f = 1 MHz,	Switch OFF, See Figure 19	25°C	1.8 V		-62		dB
Total harmonic distortion	THD	$R_L = 600 \Omega,$ $C_L = 50 pF,$	f = 20 Hz to 20 kHz See Figure 21	25°C	1.8 V	(	0.055%		
Supply									
Positive supply	$I_{CC}$ $V_1 = V_{CC}$ or GND,		Switch ON or OFF	25°C	1.95 V		0.001	0.01	μA
current	Icc	VI - VCC OI GIVD,	GWILGIT ON OF OFF	Full	1.33 V			0.15	μΛ

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.

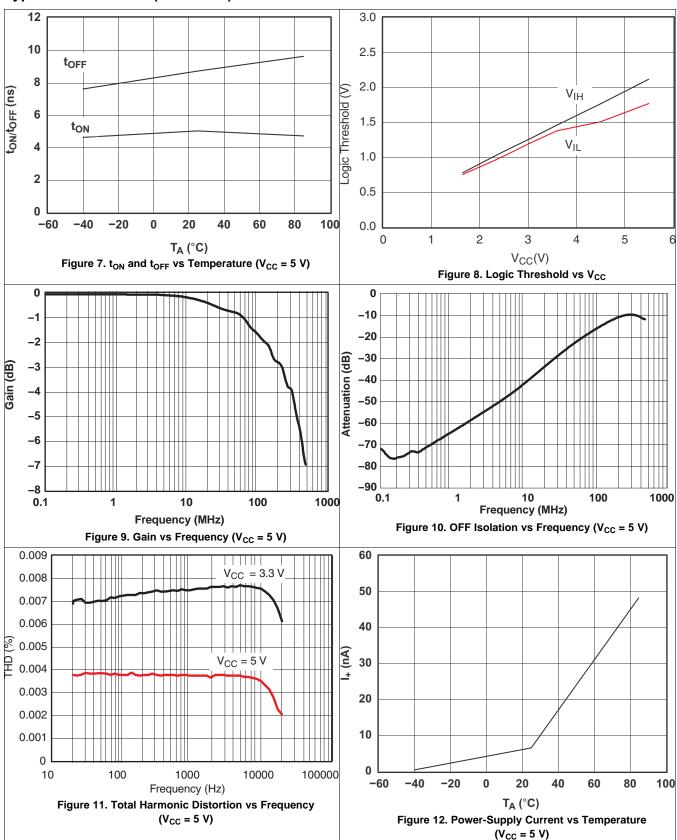


### 6.13 Typical Performance





### **Typical Performance (continued)**





### 7 Parameter Measurement Information

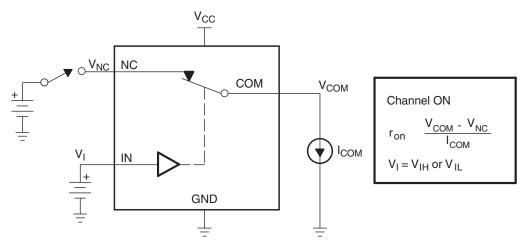


Figure 13. ON-State Resistance (ron)

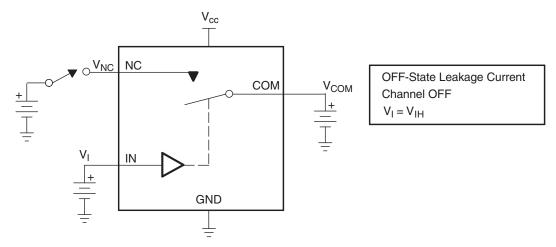


Figure 14. OFF-State Leakage Current ( $I_{COM(OFF)}$ ,  $I_{NC(OFF)}$ ,  $I_{COM(PWROFF)}$ ,  $I_{NC(PWROFF)}$ )

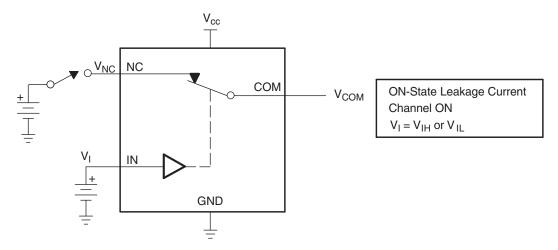


Figure 15. ON-State Leakage Current (I<sub>COM(ON)</sub>, I<sub>NC(ON)</sub>)



### **Parameter Measurement Information (continued)**

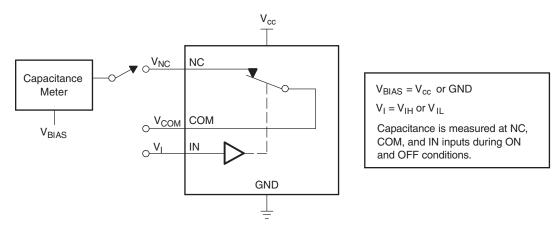
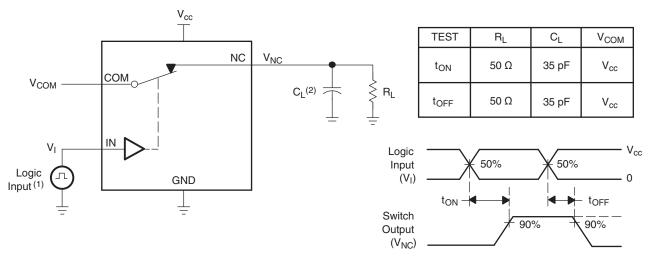


Figure 16. Capacitance (C<sub>I</sub>,  $C_{COM(OFF)}$ ,  $C_{COM(ON)}$ ,  $C_{NC(OFF)}$ ,  $C_{NC(ON)}$ )



- (1) All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f < 5 \text{ ns}$ ,  $t_f < 5 \text{ ns}$ .
- (2) C<sub>L</sub> includes probe and jig capacitance.

Figure 17. Turn-On  $(t_{ON})$  and Turn-Off Time  $(t_{OFF})$ 

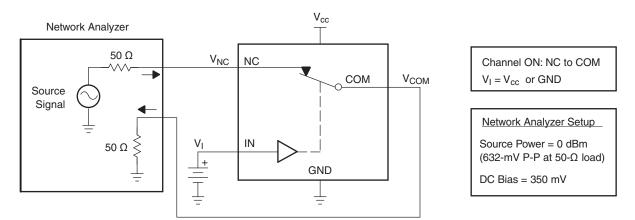


Figure 18. Bandwidth (BW)



### **Parameter Measurement Information (continued)**

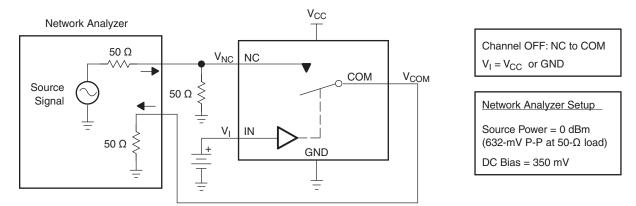
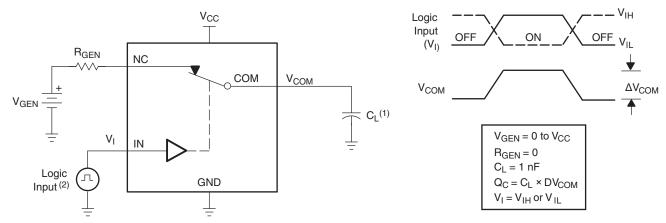
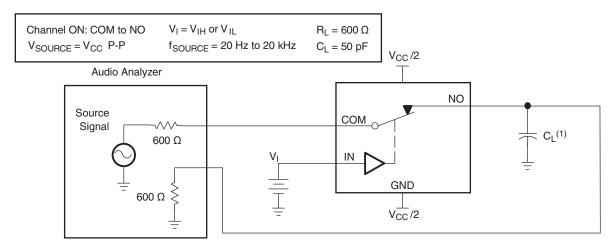


Figure 19. OFF Isolation (O<sub>ISO</sub>)



- (1) C<sub>L</sub> includes probe and jig capacitance.
- (2) All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f < 5 \text{ ns}$ ,  $t_f < 5 \text{ ns}$ .

Figure 20. Charge Injection (Q<sub>C</sub>)



(1) C<sub>L</sub> includes probe and jig capacitance.

Figure 21. Total Harmonic Distortion (THD)

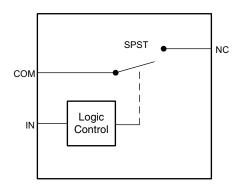


### 8 Detailed Description

#### 8.1 Overview

The TS5A3167 is a bidirectional, single-channel, single-pole single-throw (SPST) analog switch that is designed to operate from 1.65 V to 5.5 V. This device provides a signal switching solution while maintaining excellent signal integrity, which makes the TS5A3367 suitable for a wide range of applications in various markets including personal electronics, portable instrumentation, and test and measurement equipment. The device maintains the signal integrity by its low ON-state resistance, excellent ON-state resistance matching, and total harmonic distortion (THD) performance. The device consumes very low power and provides isolation when VCC = 0.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

### 8.3.1 Isolation in Powered-Off Mode, $V_{CC} = 0$

When power is not supplied to the  $V_{CC}$  pin,  $V_{CC}$  = 0 , the signal paths NC and COM are high impedance. This is specificed in the electrical characterisitics table under the COM and NC OFF leakage current when  $V_{CC}$  = 0. Because the device is high impedance when it is not powered, you may connect other signals to the signal chain without interference of the TS5A3167.

### 8.4 Device Functional Modes

Placing a logic low signal on the IN pin of the device will turn on the switch and provide a low impedance path from NC to COM.

**Table 1. Function Table** 

IN	NC TO COM, COM TO NC
L	ON
Н	OFF



### 9 Application and Implementation

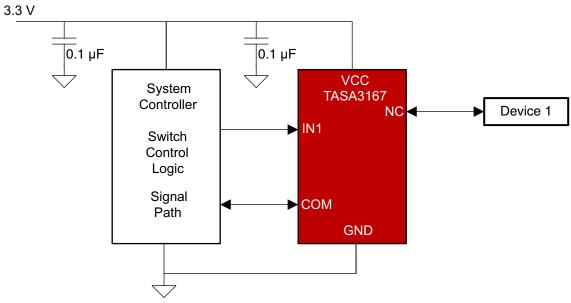
#### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

The TS5A3167 switch is bidirectional, so the NC and COM pins can be used as either inputs or outputs. This switch is typically used when there is one signal path that needs to be isolated at certian times.

### 9.2 Typical Application



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Figure 22. Typical Application

#### 9.2.1 Design Requirements

The TS5A3167 device can be properly operated without any external components.

Unused pin may be left floating or connected to ground.

TI recommends pulling up the digital control pin (IN) to  $V_{CC}$  or pulling down to GND to avoid undesired switch positions that could result from the floating pin. A floating digital pin could cause excess current consumption refer to *Implications of Slow or Floating CMOS Inputs*.

#### 9.2.2 Detailed Design Procedure

Select the appropriate supply voltage to cover the entire voltage swing of the signal passing through the switch because the TS5A3167 input and output signal swing through NC and COM are dependent on the supply voltage  $V_{CC}$ . For example, if the desired signal level to pass through the switch is 5 V,  $V_{CC}$  must be greater than or equal to 5 V.  $V_{CC} = 3.3$  V would not be valid for passing a 5-V signal since the analog signal voltage cannot exceed the supply.

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### **Typical Application (continued)**

#### 9.2.3 Application Curves

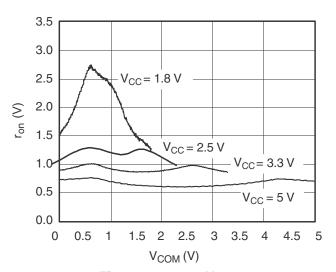


Figure 23. r<sub>on</sub> vs V<sub>COM</sub>

### 10 Power Supply Recommendations

TI recommends proper power-supply sequencing for all CMOS devices. Do not exceed the absolute maximum ratings, because stresses beyond the listed ratings can cause permanent damage to the device. It is recommended that  $V_{CC}$  is powered on first, followed by NC or COM but not required because of the Isolation in Powered-Off Mode,  $V_{CC} = 0$  feature.

Although it is not required, power-supply bypassing improves noise margin and prevents switching noise propagation from the  $V_{CC}$  supply to other components. A 0.1- $\mu$ F capacitor, connected from  $V_{CC}$  to GND, is adequate for most applications.



### 11 Layout

### 11.1 Layout Guidelines

TI recommends following common printed-circuit board layout guidelines to ensure reliability of the device.

- Bypass capacitors should be used on power supplies.
- Short trace lengths should be used to avoid excessive loading.

### 11.2 Layout Example

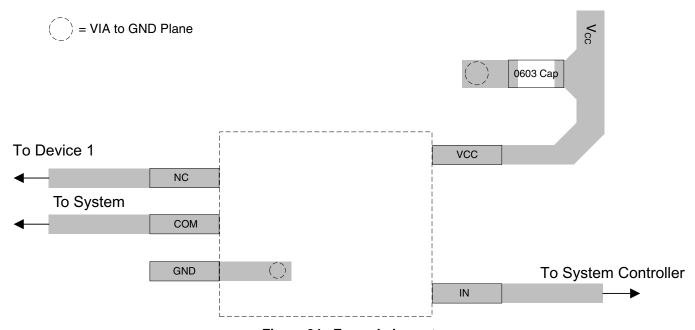


Figure 24. Example Layout



### 12 Device and Documentation Support

### 12.1 Documentation Support

**Table 2. Parameter Description** 

SYMBOL	DESCRIPTION
V <sub>COM</sub>	Voltage at COM.
V <sub>NC</sub>	Voltage at NC.
r <sub>on</sub>	Resistance between COM and NC ports when the channel is ON.
r <sub>peak</sub>	Peak on-state resistance over a specified voltage range.
r <sub>on(flat)</sub>	Difference between the maximum and minimum value of ron in a channel over the specified range of conditions.
I <sub>NC(OFF)</sub>	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the OFF state under worst-case input and output conditions.
I <sub>NC(PWROFF)</sub>	Leakage current measured at the NC port during the power-down condition, $V_{CC} = 0$ .
I <sub>COM(OFF)</sub>	Leakage current measured at the COM port, with the corresponding channel (COM to NC) in the OFF state under worst-case input and output conditions.
I <sub>COM(PWROFF)</sub>	Leakage current measured at the COM port during the power-down condition, $V_{CC} = 0$ .
I <sub>NC(ON)</sub>	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the ON state. and the output (COM) open
I <sub>COM(ON)</sub>	Leakage current measured at the COM port, with the corresponding channel (COM to NC) in the ON state. and the output (NC) open.
$V_{IH}$	Minimum input voltage for logic high for the control input (IN).
$V_{IL}$	Maximum input voltage for logic low for the control input (IN).
$V_{I}$	Voltage at the control input (IN).
$I_{\rm IH},I_{\rm IL}$	Leakage current measured at the control input (IN).
t <sub>ON</sub>	Turn-on time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM or NC) signal when the switch is turning ON.
t <sub>OFF</sub>	Turn-off time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM or NC) signal when the switch is turning OFF.
$Q_{\mathbb{C}}$	Charge injection is a measurement of unwanted signal coupling from the control (IN) input to the analog (NC or COM) output. This is measured in coulombs (C) and measured by the total charge induced due to switching of the control input. Charge injection, $Q_C = C_L \times \Delta V_{COM}$ , $C_L$ is the load capacitance, and $\Delta V_{COM}$ is the change in analog output voltage.
C <sub>NC(OFF)</sub>	Capacitance at the NC port when the corresponding channel (NC to COM) is OFF.
C <sub>COM(OFF)</sub>	Capacitance at the COM port when the corresponding channel (COM to NC) is OFF.
C <sub>NC(ON)</sub>	Capacitance at the NC port when the corresponding channel (NC to COM) is ON.
C <sub>COM(ON)</sub>	Capacitance at the COM port when the corresponding channel (COM to NC) is ON.
C <sub>I</sub>	Capacitance of control input (IN).
O <sub>ISO</sub>	OFF isolation of the switch is a measurement of OFF-state switch impedance. This is measured in dB in a specific frequency, with the corresponding channel (NC to COM) in the OFF state.
BW	Bandwidth of the switch. This is the frequency in which the gain of an ON channel is -3 dB below the DC gain.
THD	Total harmonic distortion describes the signal distortion caused by the analog switch. This is defined as the ratio of root mean square (RMS) value of the second, third, and higher harmonic to the absolute magnitude of the fundamental harmonic.
I <sub>CC</sub>	Static power-supply current with the control (IN) pin at V <sub>CC</sub> or GND.
	+

## 12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 12.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

Submit Documentation Feedback

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### **Community Resources (continued)**

TI E2E™ Online Community TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

#### 12.4 Trademarks

E2E is a trademark of Texas Instruments.

### 12.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 12.6 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

### 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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Product Folder Links: *TS5A3167* 

www.ti.com 30-Aug-2021

#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TS5A3167DBVR	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 85	(JATF, JATR) (JATH, JATP)	Samples
TS5A3167DBVRE4	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	JATF	Samples
TS5A3167DBVRG4	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	JATF	Samples
TS5A3167DCKR	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(JG5, JGF, JGR) (JGH, JGP, JGS)	Samples
TS5A3167DCKRG4	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(JG5, JGF, JGR) (JGH, JGP, JGS)	Samples
TS5A3167YZPR	ACTIVE	DSBGA	YZP	5	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	JGN	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



### **PACKAGE OPTION ADDENDUM**

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(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

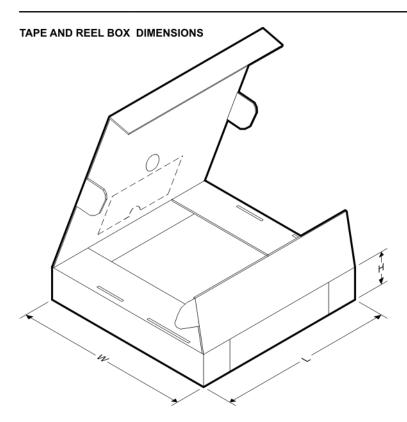
### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TS5A3167DBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
TS5A3167DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TS5A3167DBVRG4	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TS5A3167DCKR	SC70	DCK	5	3000	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
TS5A3167DCKR	SC70	DCK	5	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
TS5A3167YZPR	DSBGA	YZP	5	3000	178.0	9.2	1.02	1.52	0.63	4.0	8.0	Q1

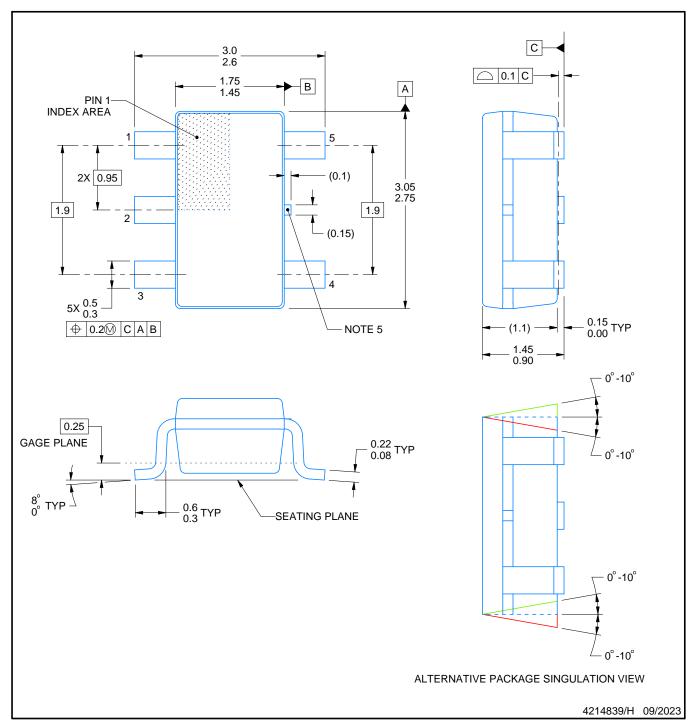
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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS5A3167DBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
TS5A3167DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TS5A3167DBVRG4	SOT-23	DBV	5	3000	180.0	180.0	18.0
TS5A3167DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
TS5A3167DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
TS5A3167YZPR	DSBGA	YZP	5	3000	220.0	220.0	35.0



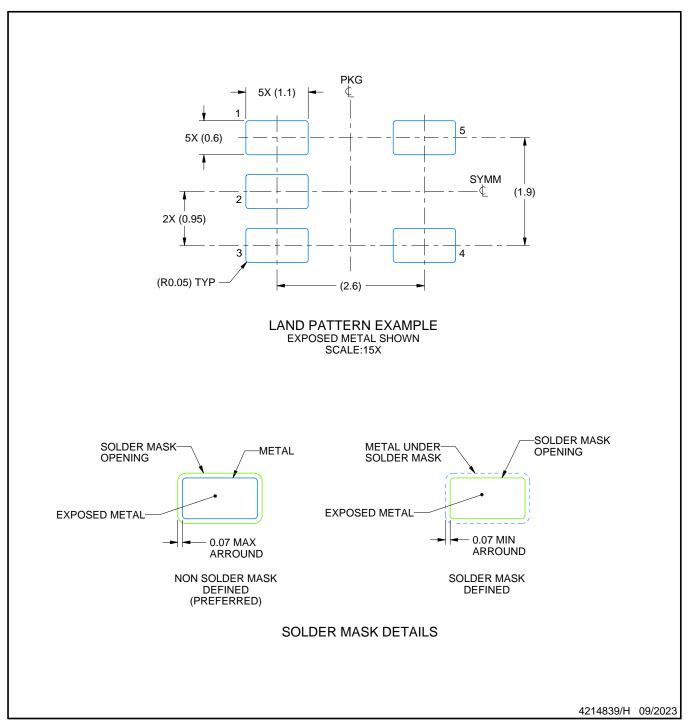


#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
  2. This drawing is subject to change without notice.
  3. Refernce JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- 5. Support pin may differ or may not be present.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



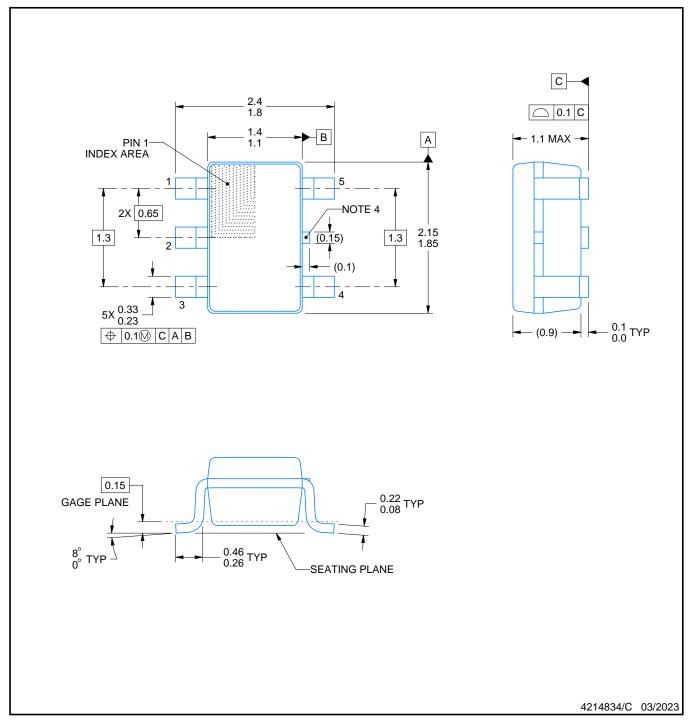


NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.







### NOTES:

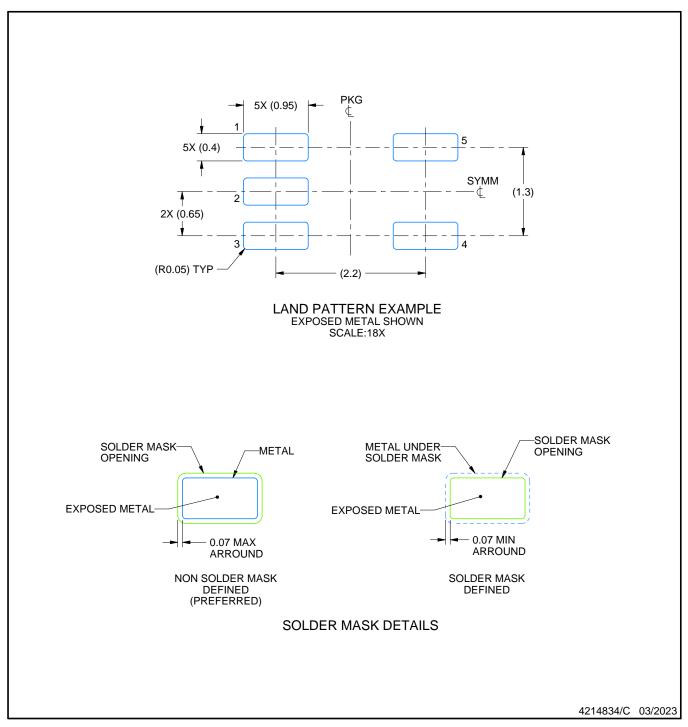
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. Reference JEDEC MO-203.

- 4. Support pin may differ or may not be present.

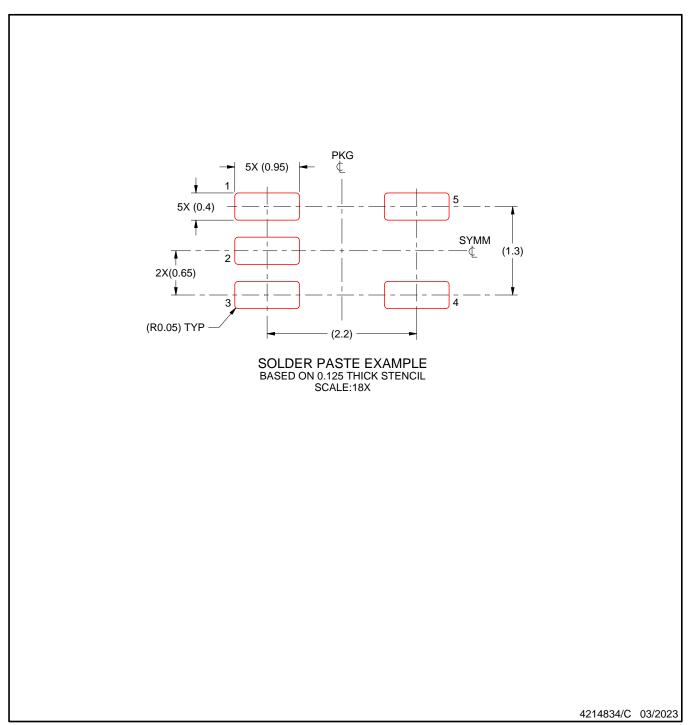




NOTES: (continued)

4. Publication IPC-7351 may have alternate designs.5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 7. Board assembly site may have different recommendations for stencil design.





DIE SIZE BALL GRID ARRAY



### NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.



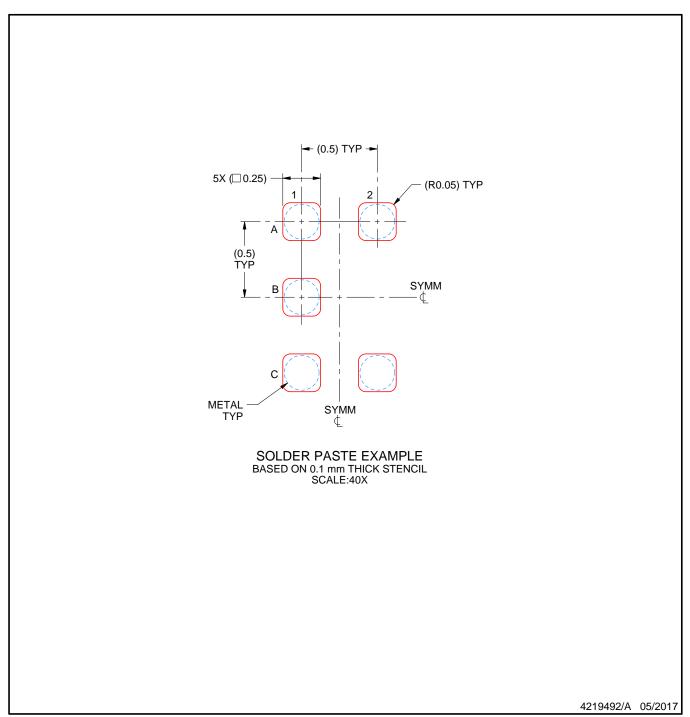
DIE SIZE BALL GRID ARRAY



NOTES: (continued)

3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 (www.ti.com/lit/snva009).

DIE SIZE BALL GRID ARRAY



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.



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